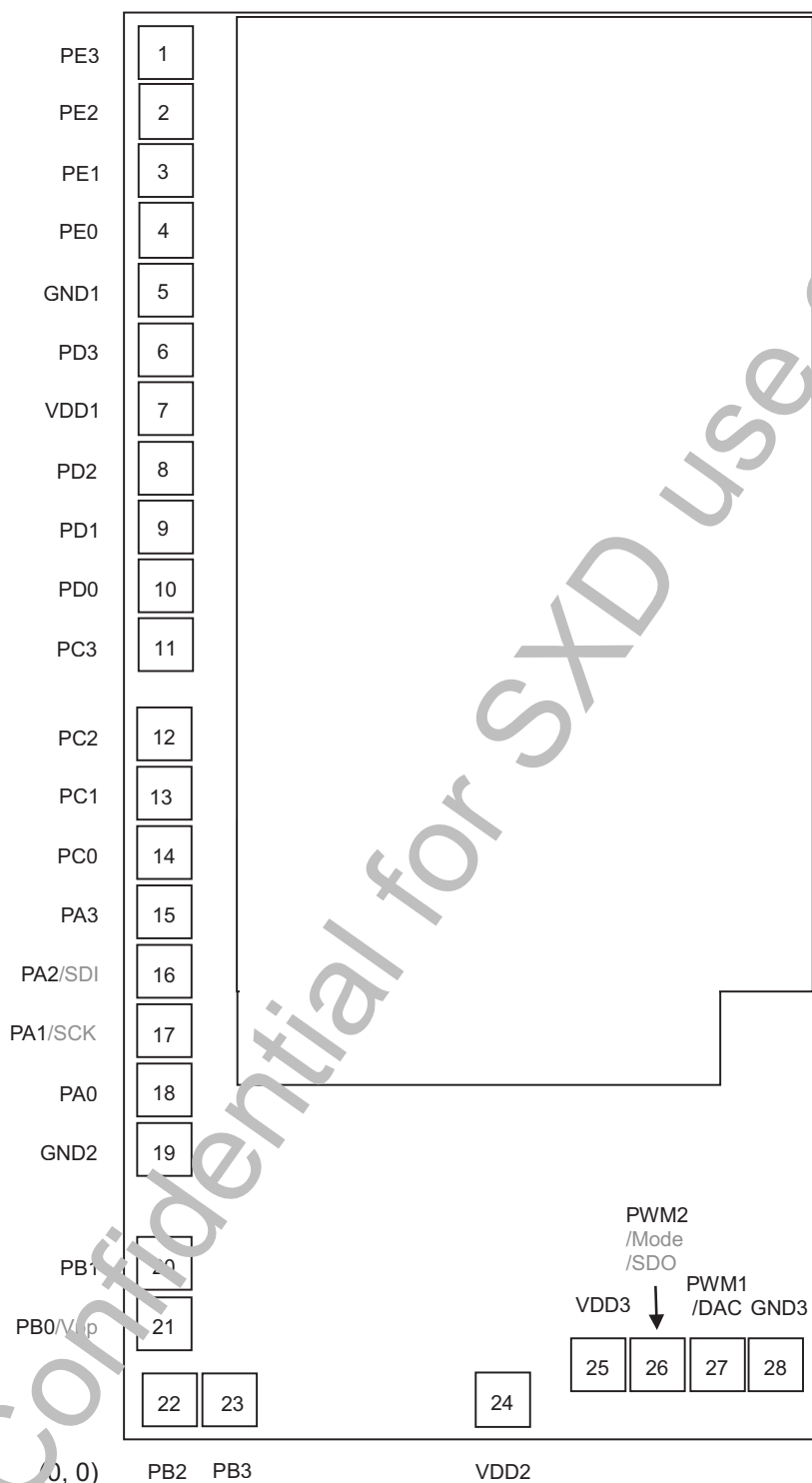




Chip size: X=972 + 60 um, Y=1994 + 60 um

Pad size: 72 um x 74 um, 74 um x 74 um

Pad No.	Pad Name	X	Y	Pad No.	Pad Name	X	Y
1	PE3	58	1937	15	PA3	58	738
2	PE2	58	1854	16	PA2 / SDI	58	655
3	PE1	58	1772	17	PA1 / SCK	58	572
4	PE0	58	1689	18	PA0	58	490
5	GND1	58	1606	19	GND2	58	406
6	PD3	58	1523	20	PB1	58	248
7	VDD1	58	1440	21	PB0 / Vpp	58	165
8	PD2	58	1358	22	PB2	63	58
9	PD1	58	1275	23	PB3	146	58
10	PD0	58	1192	24	VDD2	527	58
11	PC3	58	1109	25	VDD3	661	106
12	PC2	58	986	26	PWM2 / Mode / SDI	744	106
13	PC1	58	903	27	PWM1/DAC	827	106
14	PC	58	820	28	GND3	909	106

* IC substrate must be connected to GND or floating.

**Both SDI from PA2 or PB2 can work for programming, please check datasheet for detail.